

Title (en)  
Device for treating a substrate web

Title (de)  
Vorrichtung zum Behandeln einer Substratbahn

Title (fr)  
Dispositif destiné au traitement d'une bande de substrat

Publication  
**EP 2063206 A3 20140402 (DE)**

Application  
**EP 08020125 A 20081119**

Priority  
DE 202007016425 U 20071122

Abstract (en)  
[origin: EP2063206A2] The device has a housing (11), which comprises a treatment section for the substrate strip (60), an inflow (13) and an outflow for a medium. A guide roller (20) is arranged in the treatment section for the transport of the substrate strip. The guide roller is equipped with a cleaning nozzle, by which liquid or gaseous cleaning substances is conducted in the treatment section for cleaning purposes. An independent claim is also included for a drying unit with multiple devices arranged in moving direction of the substrate strip.

IPC 8 full level  
**F26B 13/10** (2006.01); **B05B 1/20** (2006.01); **B08B 3/02** (2006.01); **F26B 13/14** (2006.01); **F26B 25/00** (2006.01)

CPC (source: EP)  
**B08B 3/022** (2013.01); **F26B 13/10** (2013.01); **F26B 13/14** (2013.01); **F26B 25/00** (2013.01); **B05B 1/20** (2013.01)

Citation (search report)

- [XA] WO 02093096 A1 20021121 - VOITH PAPER PATENT GMBH [DE], et al
- [XAYI] DE 10335750 A1 20050303 - VOITH PAPER PATENT GMBH [DE]
- [Y] US 6134811 A 20001024 - BERGER BERND [DE], et al
- [X] EP 1118707 A1 20010725 - VALMET INC [US]
- [A] US 5077913 A 19920107 - AKERBLOM MIKAEL [SE], et al
- [A] DE 10361539 A1 20050728 - TESA AG [DE]

Cited by  
CN110500866A; CN114877652A

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)  
AL BA MK RS

DOCDB simple family (publication)  
**DE 202007016425 U1 20080131**; EP 2063206 A2 20090527; EP 2063206 A3 20140402; EP 2063206 B1 20161005

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**DE 202007016425 U 20071122**; EP 08020125 A 20081119